

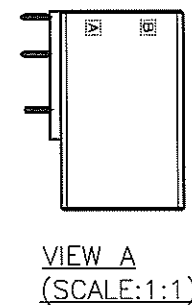
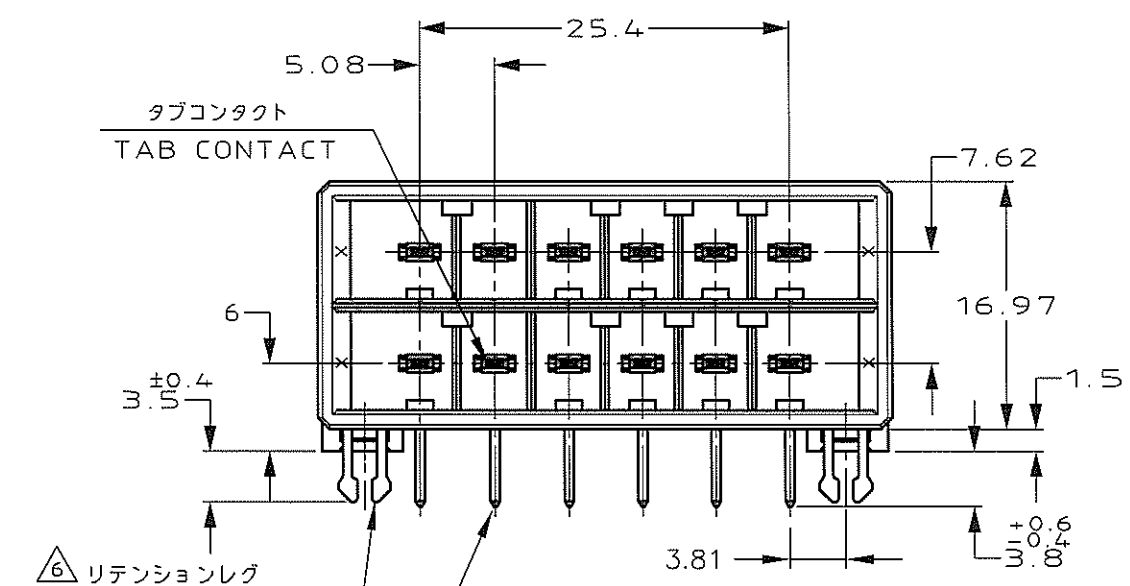
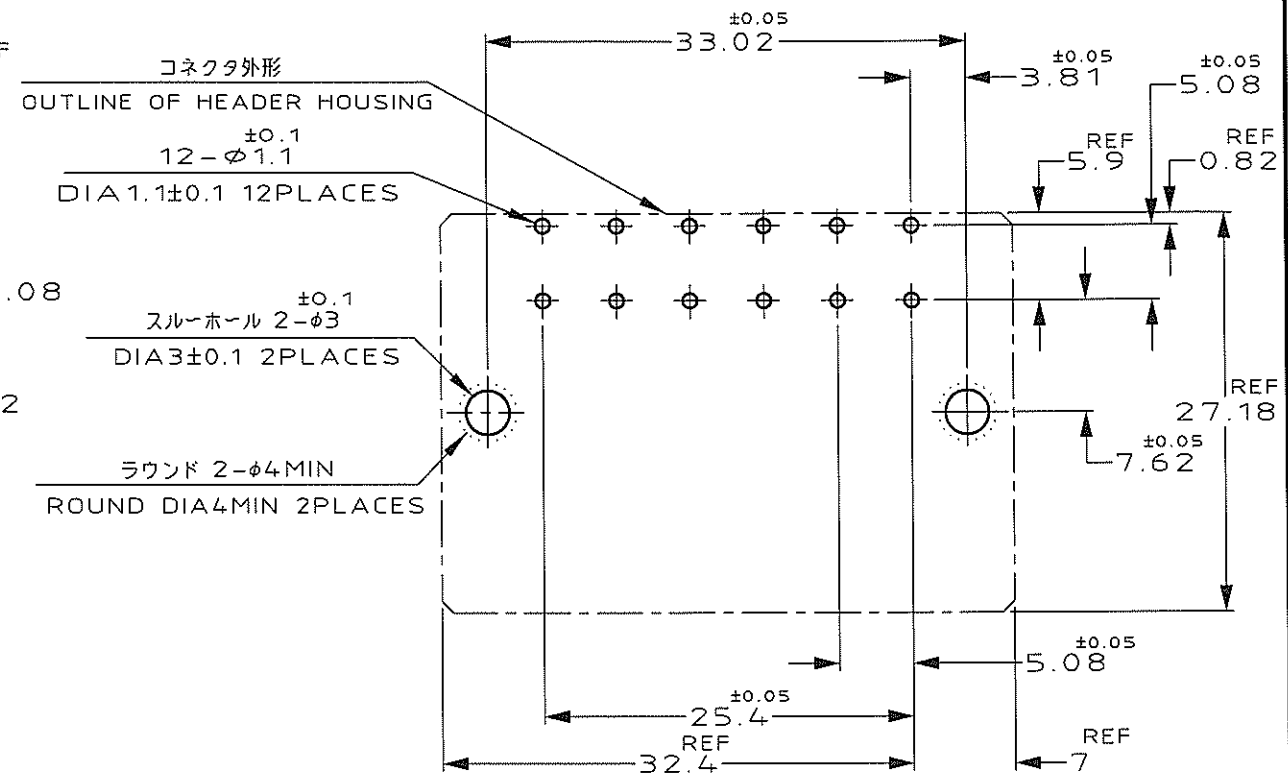
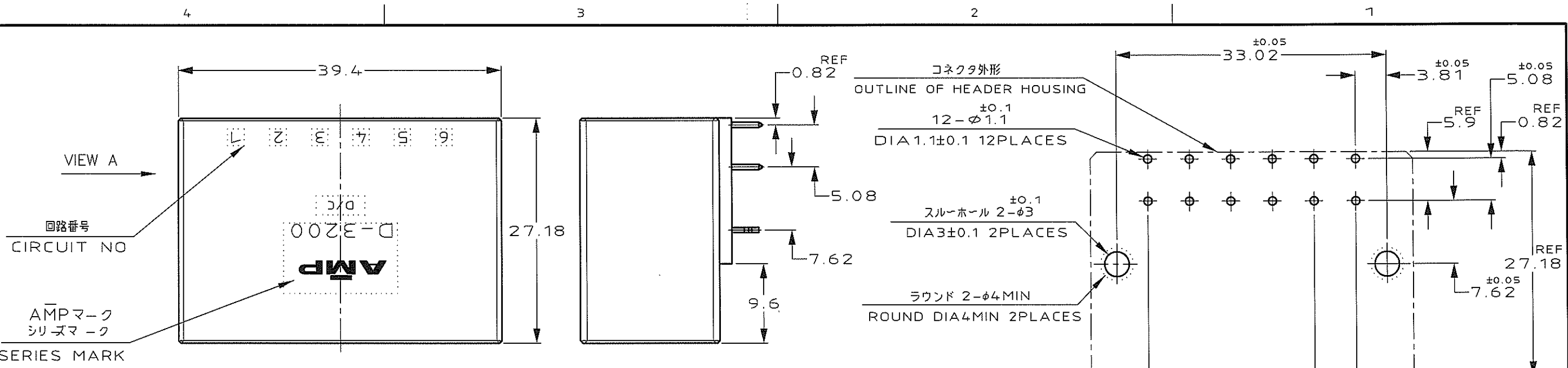
NUMBER 316081

3rd ANGLE PROJECTION

METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け穴寸法
PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

注記
1. 材料: ハウジング: ガラス入り熱可塑性
ポリエステル樹脂 (94V-0), 色: 黒
コンタクト: 銅合金
リテンションレグ: 銅合金

△2. めっき: コンタクト: 全面Ni下地
接触部: 0.38 μm MIN金めっき

△3. めっき: コンタクト: 全面Ni下地
接触部: 0.76 μm MIN金めっき

△4. めっき: コンタクト: 全面Ni下地
接触部: 2.0 μm MINスズめっき

△5. めっき: リテンションレグとコンタクト半田付部
ニッケル下地の上に半田めっき

△6. めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

NOTES
1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY

△2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING

△3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING

△4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL

△5. FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL

△6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

△7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

KEYING LOCATION	A ROW KEYING	B ROW KEYING	FINISH	製品番号	PART NO.
B ROW	X	Y	△6 △4	3-316081-5	△7
A ROW			△6 △3	3-316081-3	
			△6 △2	3-316081-2	
B ROW	Y	Y	△6 △4	2-316081-5	
A ROW			△6 △3	2-316081-3	
			△6 △2	2-316081-2	
B ROW	X	X	△6 △4	1-316081-5	
A ROW			△6 △3	1-316081-3	
			△6 △2	1-316081-2	

WIRE RANGE		INSULATION DIA		NAME	
mm? (AWG)		mmφ		12 POS DOUBLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 4/JUL/95 K.IKEDA		DE. 4/JUL/95 K.IKEDA		10% ±0.3	SIZE LOC NUMBER
CHK. 4/JUL/95 Y.ISHIKAWA		APP. 4/JUL/95 S.MANABE		10% ±0.4	A3 J C-316081
B4 REVISED PER ECO-11-005030		RK HMR 20MAR 11		30% ±0.45	SCALE REV. SHEET
LTR REVISION RECORD		DR CHK DATE		±3'	2-1 B4 1 OF 1